

Ceramic Plate Series Thermoelectric Cooler

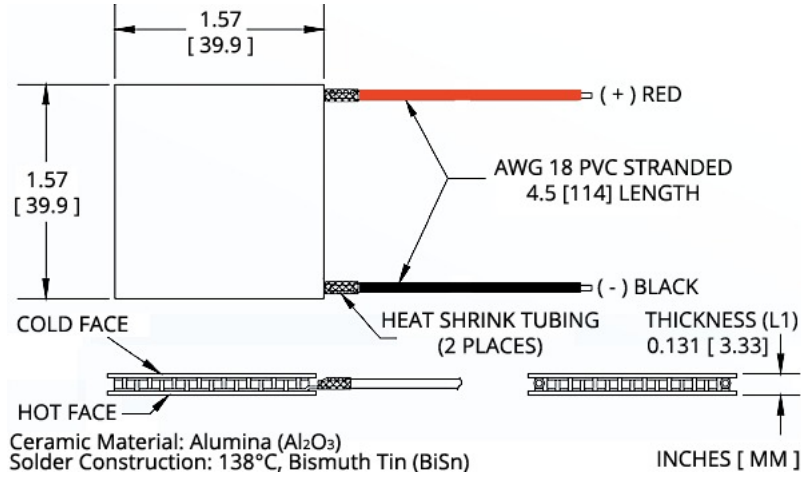
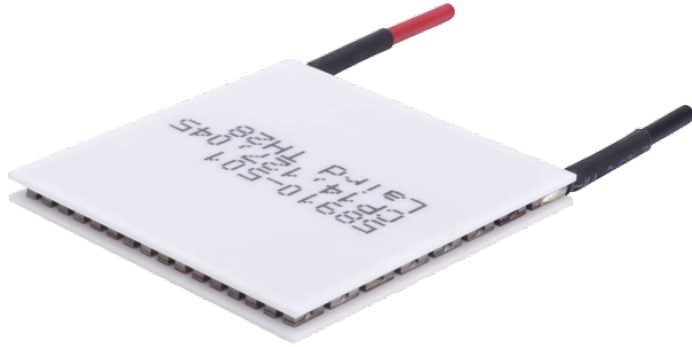
The CP14-127-045-L1-EP-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Q_c of 71.3 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at $Q_c = 0$.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

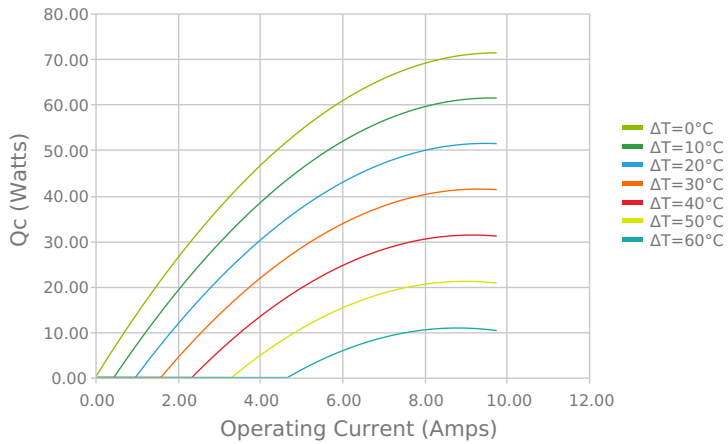
- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision



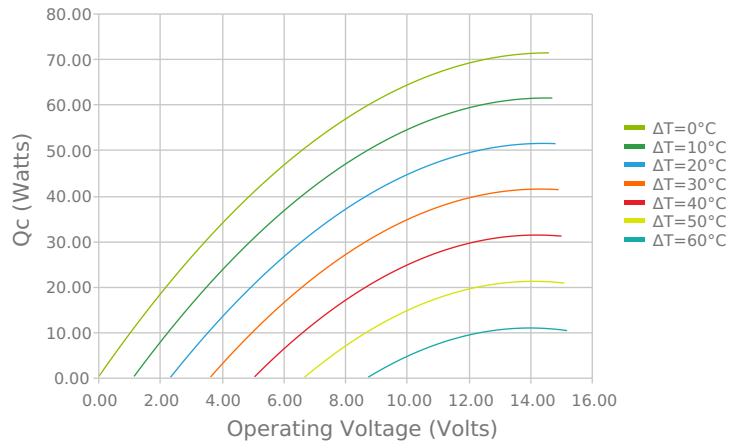
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

ELECTRICAL AND THERMAL PERFORMANCE

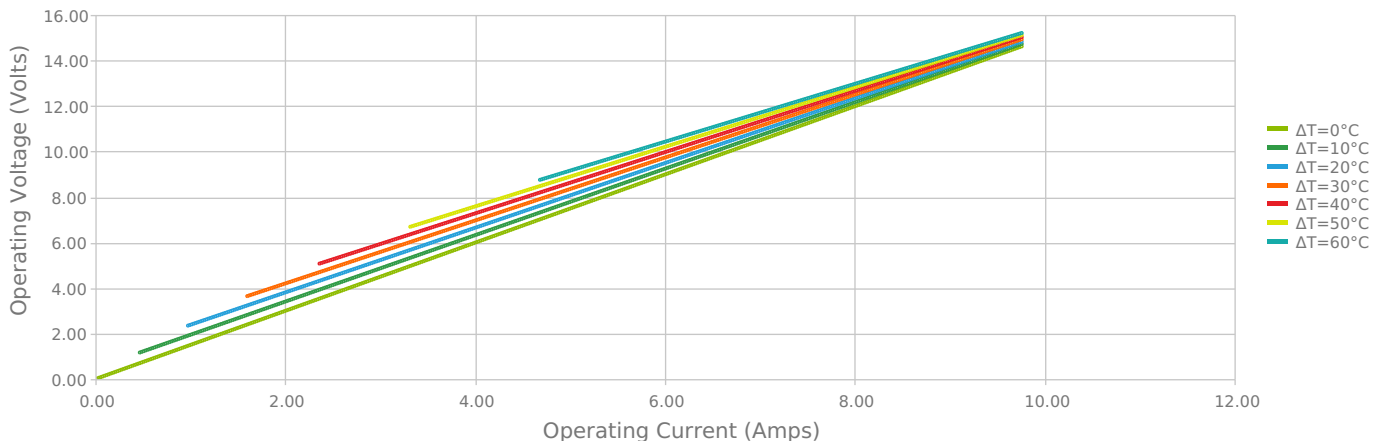
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



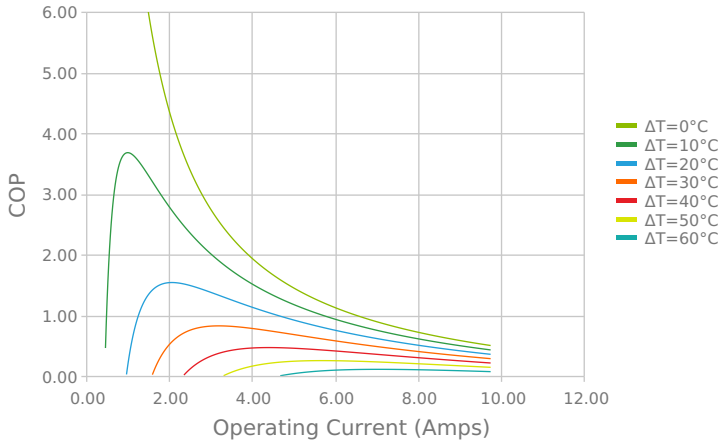
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



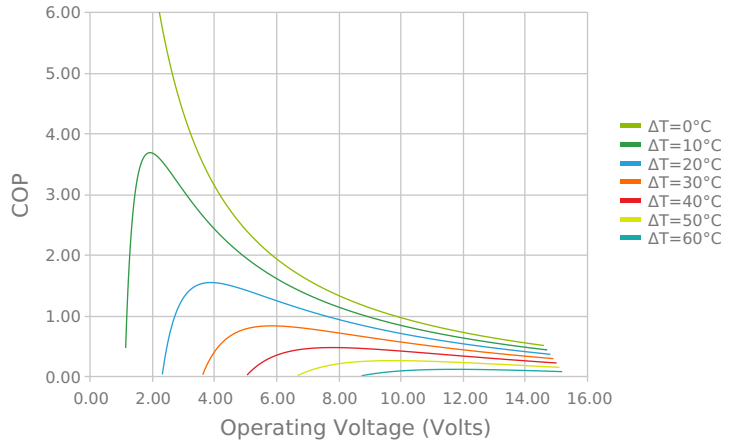
Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



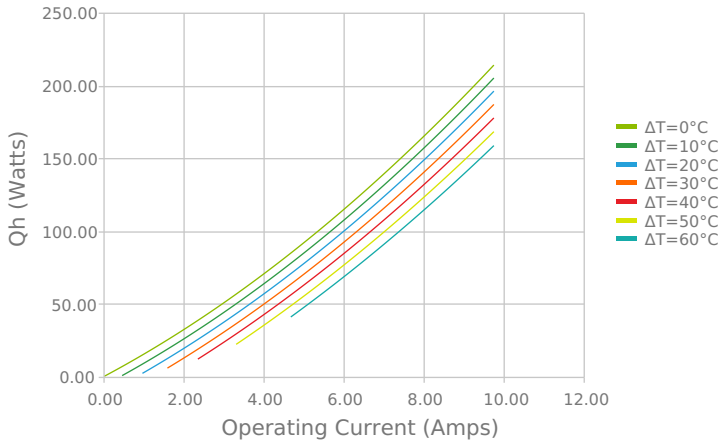
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



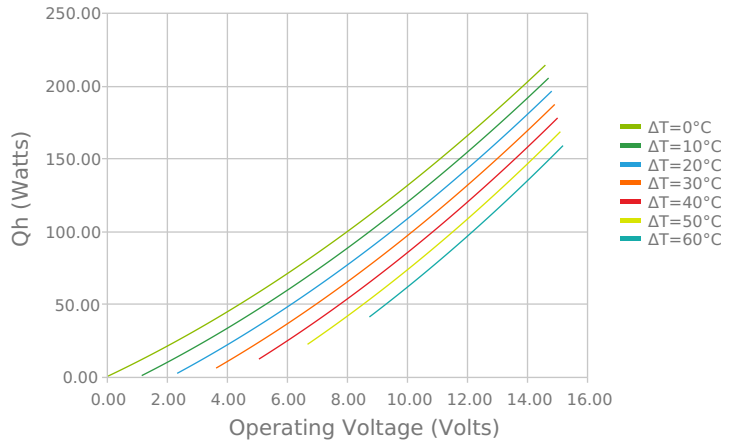
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



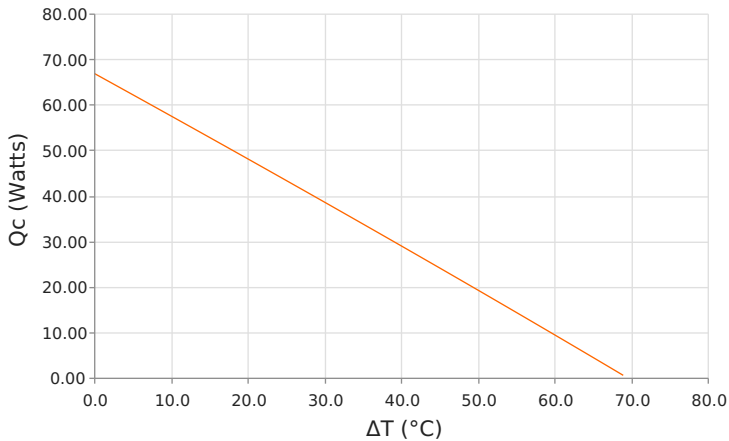
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



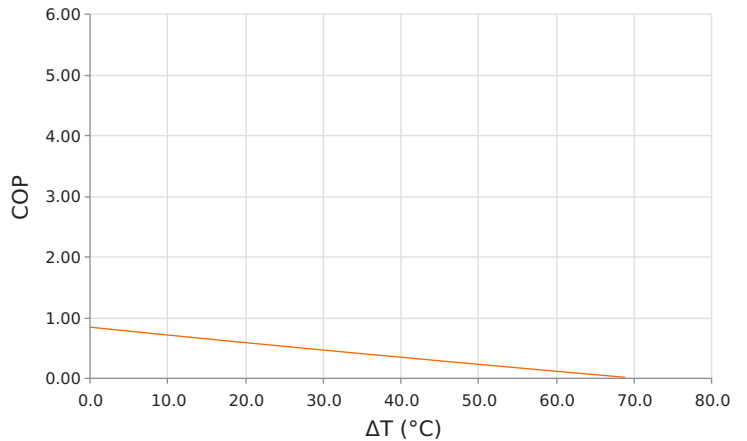
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



Heat Pumped at Cold Side (Qc)
 Thot = 27 °C | Current = 7.3 Amps



Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C | Current = 7.3 Amps



SPECIFICATIONS*

| | 27.0 °C | 35.0 °C | 50.0 °C |
|---|--------------|------------|------------|
| Hot Side Temperature | | | |
| Qcmax ($\Delta T = 0$) | 71.3 Watts | 73.5 Watts | 77.3 Watts |
| ΔT_{max} ($Q_c = 0$) | 70.5°C | 73.5°C | 78.8°C |
| I_{max} (I @ ΔT_{max}) | 8.6 Amps | 8.6 Amps | 8.5 Amps |
| V_{max} (V @ ΔT_{max}) | 13.9 Volts | 14.4 Volts | 15.4 Volts |
| Module Resistance | 1.50 Ohms | 1.56 Ohms | 1.68 Ohms |
| Max Operating Temperature | 80 °C | | |
| Weight | 20.0 gram(s) | | |

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

| Suffix | Thickness | Flatness / Parallelism | Hot Face | Cold Face | Lead Length |
|--------|-------------------------------------|--|----------|-----------|---------------------|
| L1 | 3.327 ±0.025 mm 0.131 ± 0.001 in | 0.025 mm / 0.025 mm 0.001 in / 0.001 in | Lapped | Lapped | 114.3 mm 4.50 in |

SEALING OPTIONS

| Suffix | Sealant | Color | Temp Range | Description |
|--------|---------|-------|--------------|--|
| EP | Epoxy | Black | -55 to 150°C | Low density syntactic foam epoxy encapsulant |

NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

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